



# SF1125A

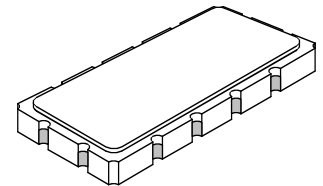
## 380 MHz SAW Filter

- **Designed for WCDMA 3G IF Applications**
- **Excellent Size-to-Performance Ratio**
- **Hermetic 13.3 x 6.5 mm Surface-mount Case**
- **Complies with Directive 2002/95/EC (RoHS)**



### Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Suitable for lead-free soldering - Max. Soldering Profile	260°C for 30 s	



SMP-53

### Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units	
Nominal Center Frequency	$f_c$	1	380.000			MHz	
Passband	Insertion Loss at $f_c$	IL		16.5	18	dB	
				1 db Passband	4.45		5.0
	3 db Passband	BW <sub>3</sub>	1, 2	5.1	5.4	MHz	
	Amplitude Ripple over $f_c \pm 2.25$ MHz			0.75	1.25	dB <sub>p-p</sub>	
	Phase Linearity over $f_c \pm 2.25$ MHz			7.5	TBD	° <sub>p-p</sub>	
Group Delay Variation over $f_c \pm 2.25$ MHz	GDV		150	175	ns <sub>p-p</sub>		
Rejection	$f_c - 3.95$ to $f_c - 3.33$ and $f_c + 3.3$ to $f_c + 3.95$ MHz	1, 2, 3	10			dB	
			$f_c - 4.125$ to $f_c - 3.95$ and $f_c + 3.95$ to $f_c + 4.125$ MHz	30			
			$f_c \pm 4.125$ to $f_c \pm 60$ MHz	40			
Part to Part Average Group Delay Variation		4			±5	nsec	
Operating Temperature Range	T <sub>A</sub>	1	-10	+25	+85	°C	
Frequency Temperature Coefficient	FTC			-18		ppm/°C	

Matching to 50Ω Balanced or Single Ended Impedance	External L-C
Case Style	SMP-53 13.3 x 6.5 mm Nominal Footprint
Lid Symbolization (YY = year, WW = week)	RFM SF1125A YYWW

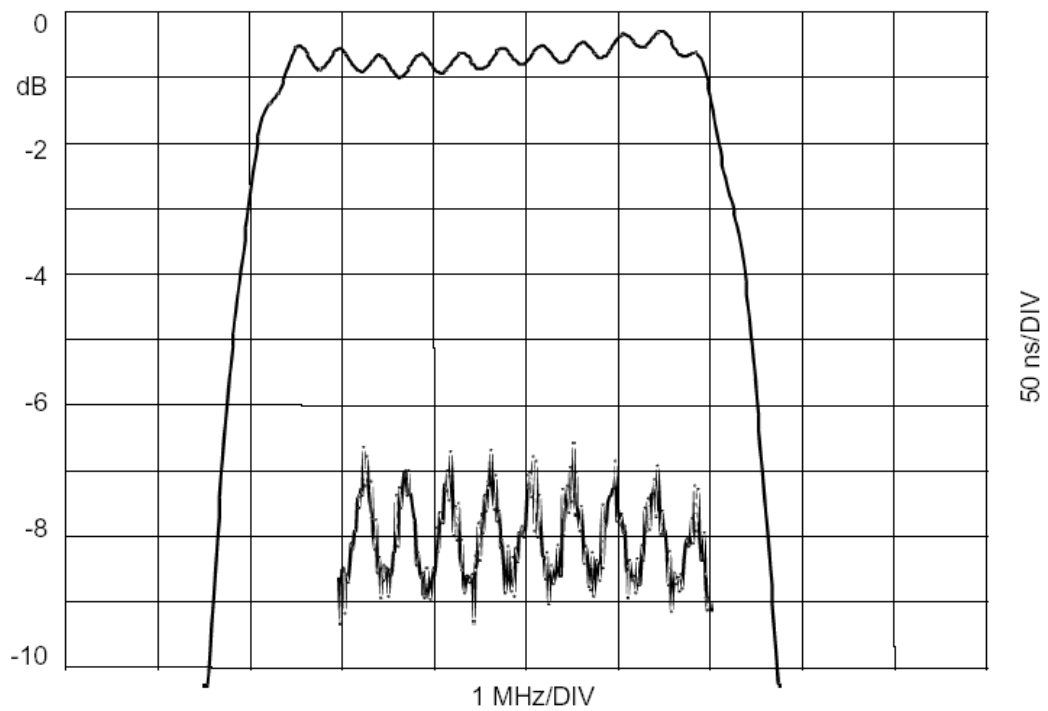
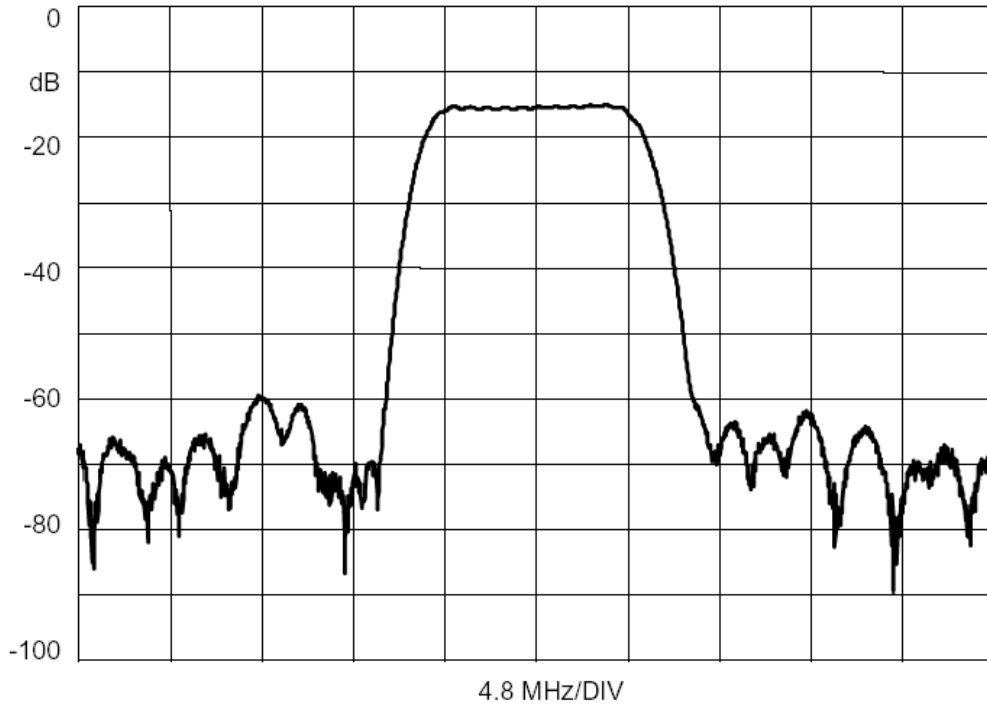
### Notes:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency,  $f_c$ .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. Part to part absolute delay measurement records the absolute delay mean across 1 dB passband.
5. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
6. The design, manufacturing process, and specifications of this filter are subject to change.
7. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
8. US and international patents may apply.
9. Electrostatic Sensitive Device. Observe precautions for handling.



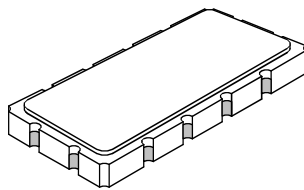
### Electrical Connections

Connection	Terminals
Port 1 Hot	11
Port 1 Gnd Return	12
Port 2 Hot	5
Port 2 Gnd Return	6
Case Ground	All others



SMP-53 Case

12-Terminal Ceramic Surface-Mount Case  
13.3 x 6.5 mm Nominal Footprint



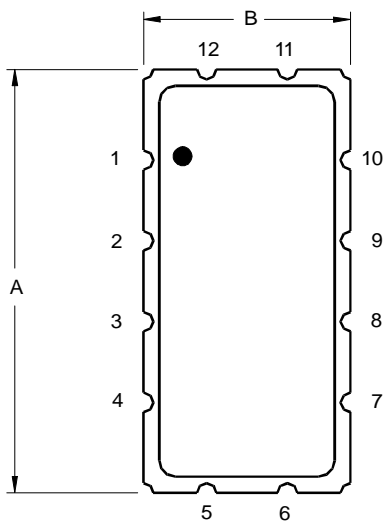
Case Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	13.08	13.31	13.60	0.515	0.524	0.535
B	6.27	6.50	6.80	0.247	0.256	0.268
C		1.91	2.00		0.075	0.079
D		1.50			0.059	
E		0.79			0.031	
H		1.0			0.039	
P		2.54			0.100	

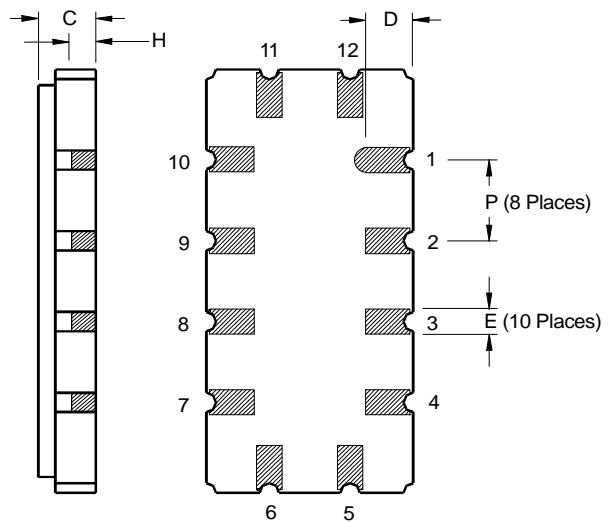
Materials	
Solder Pad Termination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic
Pb Free	

Electrical Connections

Connection		Terminals
Port 1	Input or Return	11
	Return or Input	12
Port 2	Output or Return	5
	Return or Output	6
Ground		All others
Single Ended Operation		Return is ground
Differential Operation		Return is hot

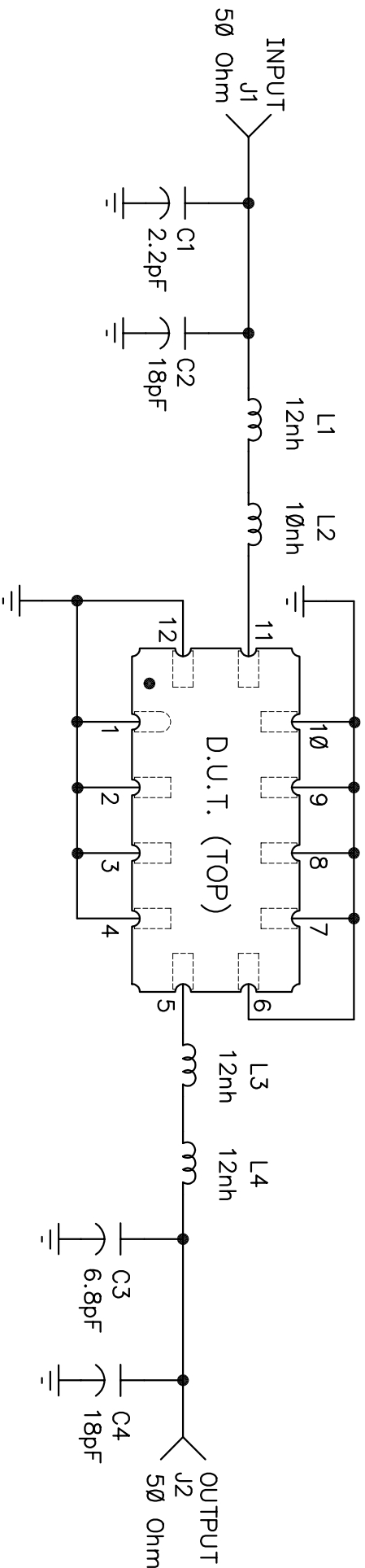


TOP VIEW



BOTTOM VIEW

REV	ECN NO.	DESCRIPTION	APP/DATE
A	9198	INITIAL RELEASE	27nov00



DRAWN BY/DATE: J.F.Christopherson 27nov00

TITLE: SF1125A DEMO PCB

**RF Monolithics, Inc.**  
DALLAS, TEXAS 75244

CHECKED/APPROVED

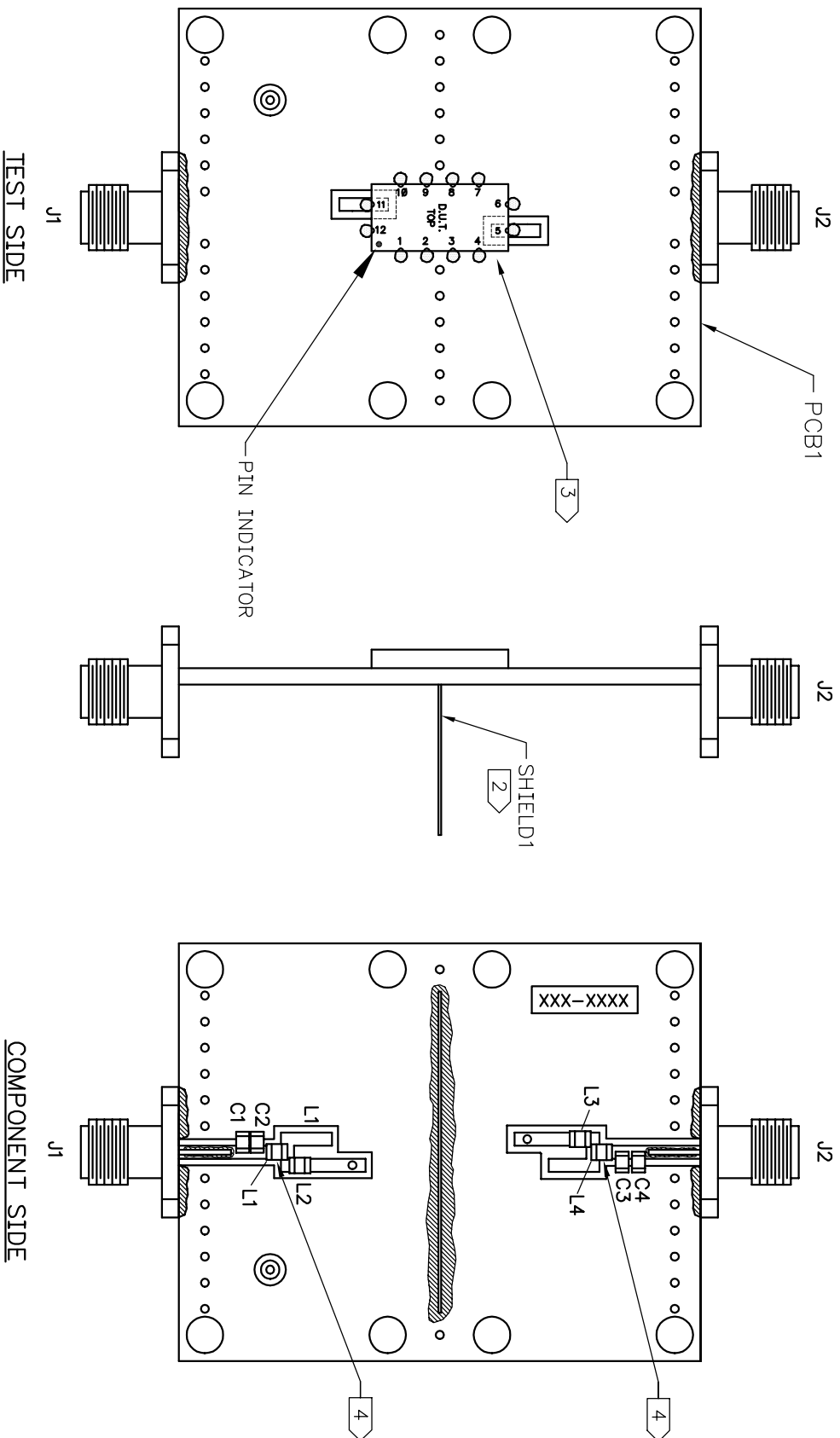
SIZE **A** CODE IDENT **2U874**

DWG. NO. **SF1125A-000**

REV **A** SHEET **1/3**

NOTES:

1. SOLDER MOUNT COMPONENTS & CONNECTORS TO PCB1.
2. SOLDER SHIELD1 AS SHOWN AND TRIM TAB FROM SHIELD SO THAT IT IS FLUSH WITH PCB.
3. ORIENT THE FLTR1 AND SOLDER IT DOWN TO THE BOARD AS SHOWN.
4. CUT TRACE TO ACCOMMODATE INDUCTOR.



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SIZE  
**A**

CODE IDENT  
**2U874**

DWG. NO.

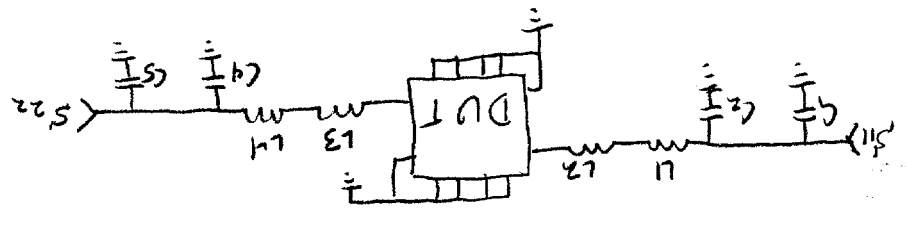
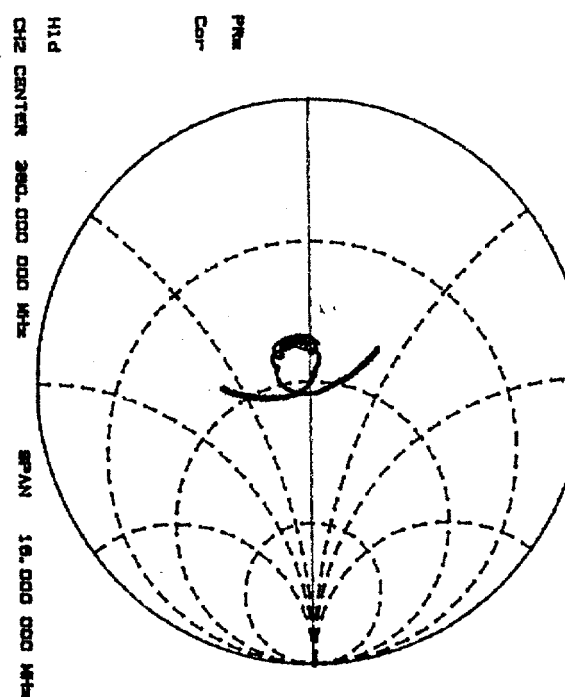
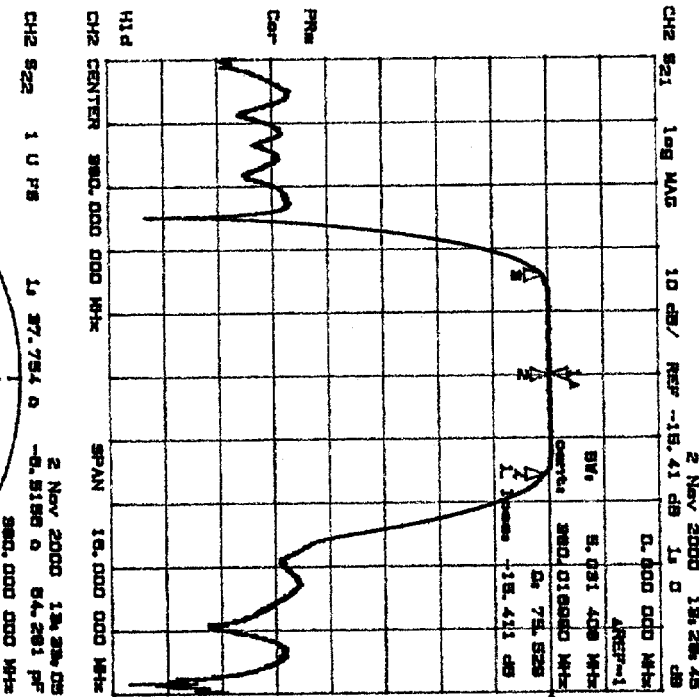
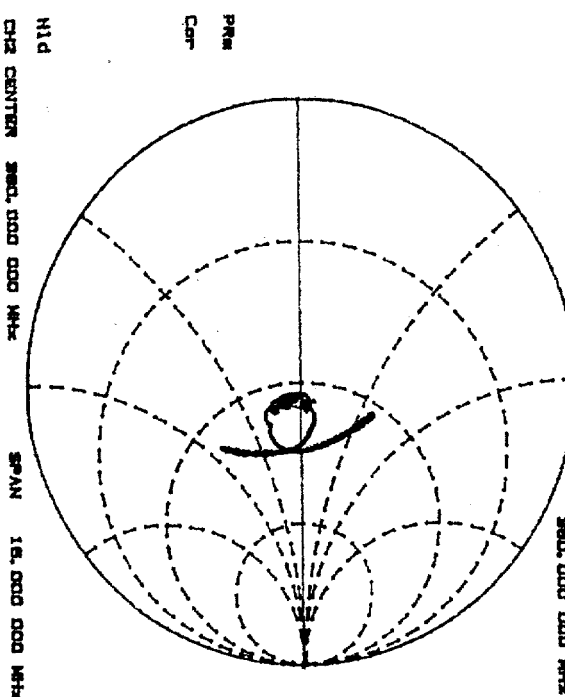
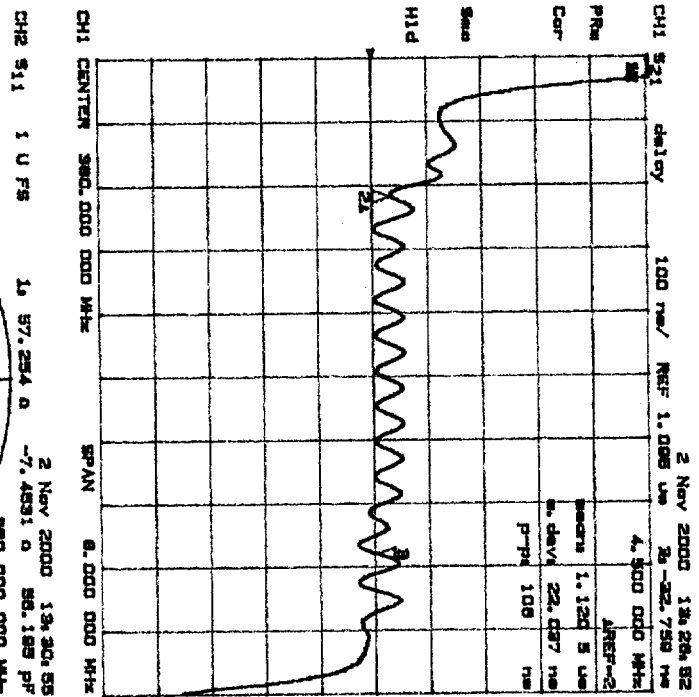
**SF1125A-000**

REV  
**A**

SHEET  
**2**

SF1125A  
 DEMO 2

11-2-00  
 RT



C1=2.2pF  
 C2=C4=18pF  
 L2=10nH  
 L1,L3,L4=12nH  
 C3=6.8pF